FAIRCHILD SEMICONDUCTOR®

April 2009

UniFET™

FDP8N60ZU / FDPF8N60ZUT

N-Channel MOSFET, FRFET

600V, 6.5A, 1.35Ω

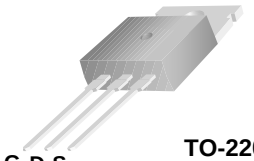
Features

- $R_{DS(on)}$ = 1.15mΩ (Typ.) @ V_{GS} = 10V, I_D = 3.25A
- Low gate charge (Typ. 20nC)
- Low C_{rss} (Typ. 10pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- RoHS compliant

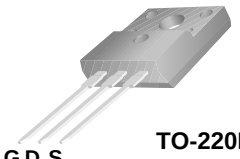
Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

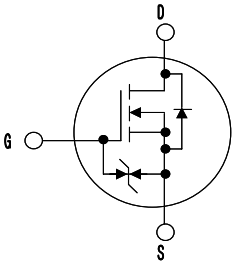
This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficient switched mode power supplies and active power factor correction.



TO-220
FDP Series



TO-220F
FDPF Series



MOSFET Maximum Ratings T_C = 25°C unless otherwise noted*

Symbol	Parameter			FDP8N60ZU	FDPF8N60ZUT	Units
V_{DSS}	Drain to Source Voltage			600		V
V_{GSS}	Gate to Source Voltage			±30		V
I_D	Drain Current	-Continuous (T_C = 25°C)		6.5	6.5*	A
		-Continuous (T_C = 100°C)		3.9	3.9*	
I_{DM}	Drain Current	- Pulsed	(Note 1)	26	26*	A
E_{AS}	Single Pulsed Avalanche Energy		(Note 2)	420		mJ
I_{AR}	Avalanche Current		(Note 1)	6.5		A
E_{AR}	Repetitive Avalanche Energy		(Note 1)	13.5		mJ
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	20		V/ns
P_D	Power Dissipation	(T_C = 25°C)		135	34.5	W
		- Derate above 25°C		1.05	0.28	W/°C
T_J, T_{STG}	Operating and Storage Temperature Range			-55 to +150		°C
T_L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds			300		°C

*Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	FDP8N60ZU	FDPF8N60ZUT	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.95	3.6	°C/W
$R_{\theta CS}$	Thermal Resistance, Case to Sink Typ.	0.5	-	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	62.5	62.5	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDP8N60ZU	FDP8N60ZU	TO-220	-	-	50
FDPF8N60ZUT	FDPF8N60ZUT	TO-220F	-	-	50

Electrical Characteristics $T_C = 25^oC$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
Off Characteristics						
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250\mu A$, $V_{GS} = 0V$, $T_J = 25^oC$	600	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu A$, Referenced to 25^oC	-	0.7	-	$V/^oC$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 600V$, $V_{GS} = 0V$	-	-	25	μA
		$V_{DS} = 480V$, $T_C = 125^oC$	-	-	250	
I_{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 30V$, $V_{DS} = 0V$	-	-	±10	μA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 250\mu A$	3.0	-	5.0	V
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10V$, $I_D = 3.25A$	-	1.15	1.35	Ω
g_{FS}	Forward Transconductance	$V_{DS} = 40V$, $I_D = 3.25A$	-	7	-	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS} = 25V$, $V_{GS} = 0V$, f = 1MHz	-	950	1265	pF
C_{oss}	Output Capacitance		-	110	150	pF
C_{rss}	Reverse Transfer Capacitance		-	10	15	pF
Q_g	Total Gate Charge at 10V	$V_{DS} = 480V$, $I_D = 6.5A$, $V_{GS} = 10V$ (Note 4)	-	20	26	nC
Q_{gs}	Gate to Source Gate Charge		-	5	-	nC
Q_{gd}	Gate to Drain “Miller” Charge		-	8	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 300V$, $I_D = 6.5A$, $R_G = 25\Omega$, $V_{GS} = 10V$ (Note 4)	-	20	50	ns
t_r	Turn-On Rise Time		-	30	70	ns
$t_{d(off)}$	Turn-Off Delay Time		-	55	120	ns
t_f	Turn-Off Fall Time		-	35	80	ns
Drain-Source Diode Characteristics						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	6.5	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	26	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0V$, $I_{SD} = 6.5A$	-	-	1.6	V
t_{rr}	Reverse Recovery Time	$V_{GS} = 0V$, $I_{SD} = 6.5A$, $dI_F/dt = 100A/\mu s$	-	40	-	ns
Q_{rr}	Reverse Recovery Charge		-	42	-	nC

Notes:
1: Repetitive Rating: Pulse width limited by maximum junction temperature
2: L = 20mH, $I_{AS} = 6.5A$, $V_{DD} = 50V$, $R_G = 25\Omega$, Starting $T_J = 25°C$
3: $I_{SD} \le 6.5A$, $di/dt \le 200A/\mu s$, $V_{DD} \le BV_{DSS}$, Starting $T_J = 25°C$
4: Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

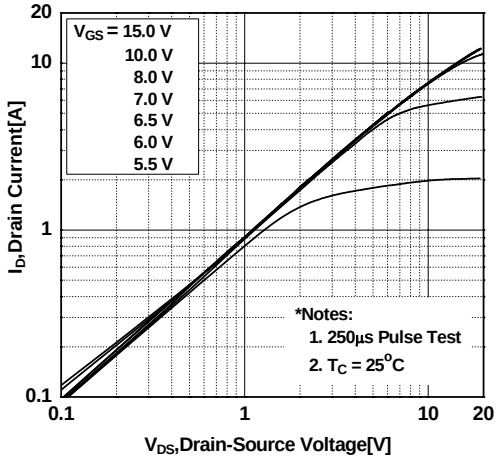


Figure 2. Transfer Characteristics

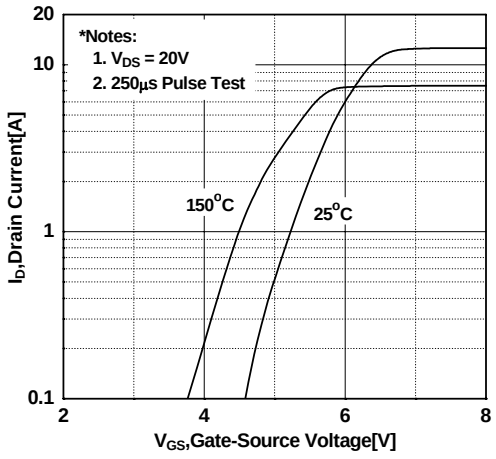


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

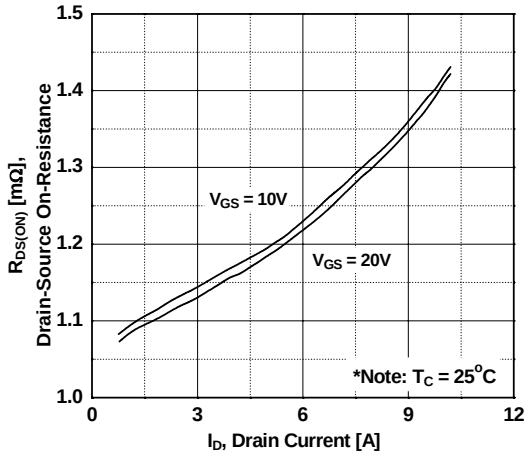


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

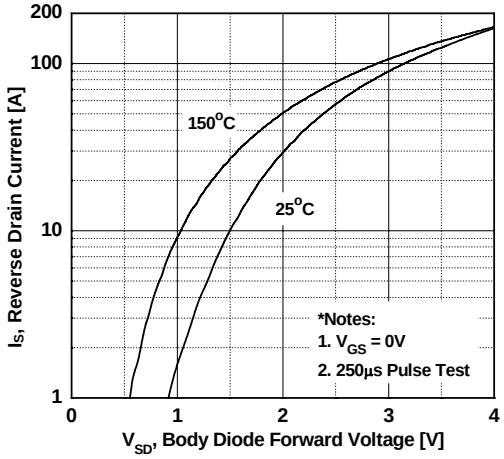


Figure 5. Capacitance Characteristics

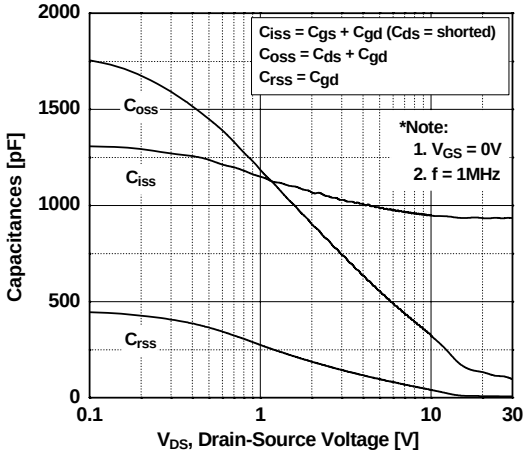
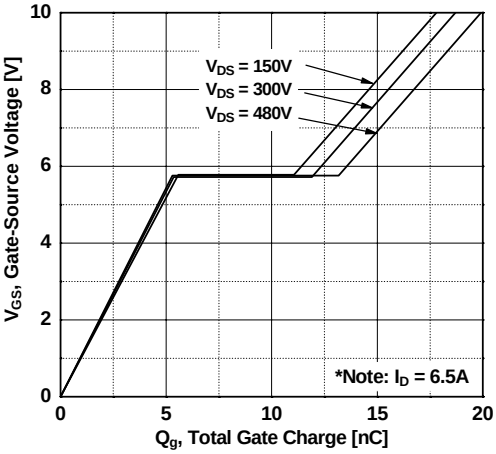


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

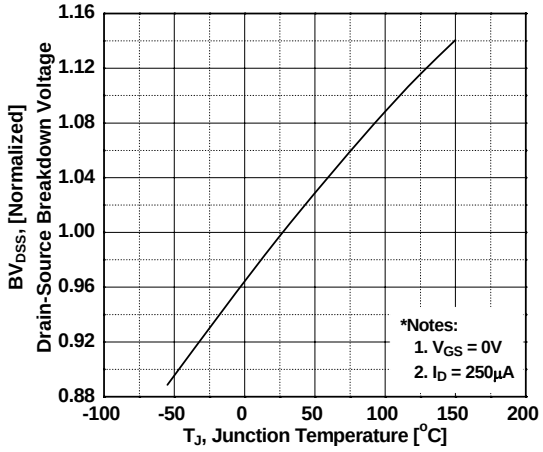


Figure 8. Maximum Safe Operating Area - FDPF8N60ZUT

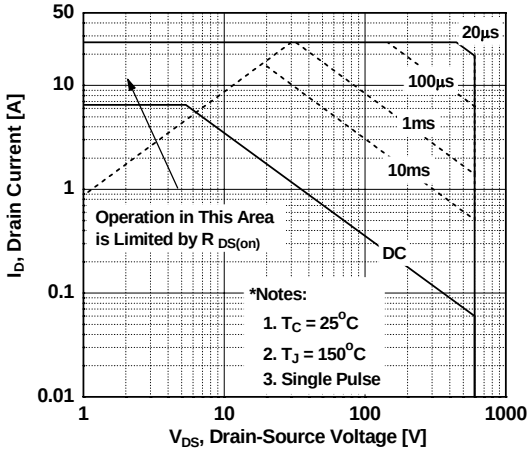


Figure 9. Maximum Drain Current vs. Case Temperature

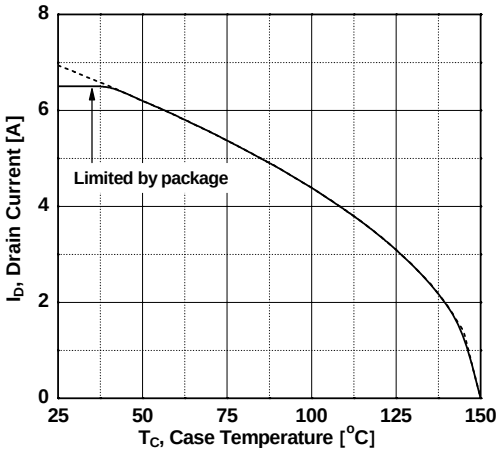
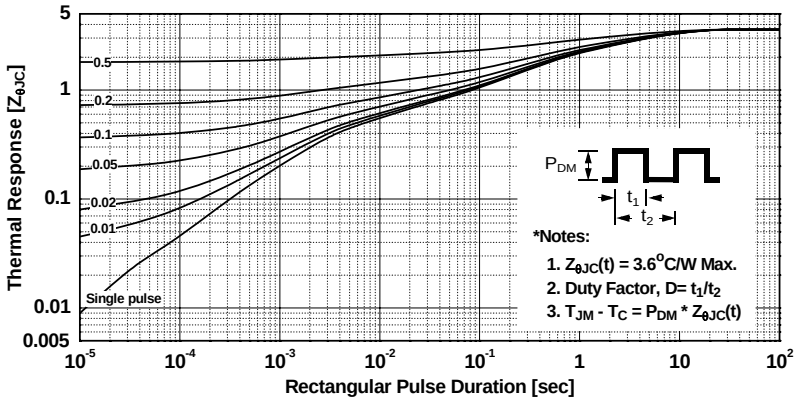
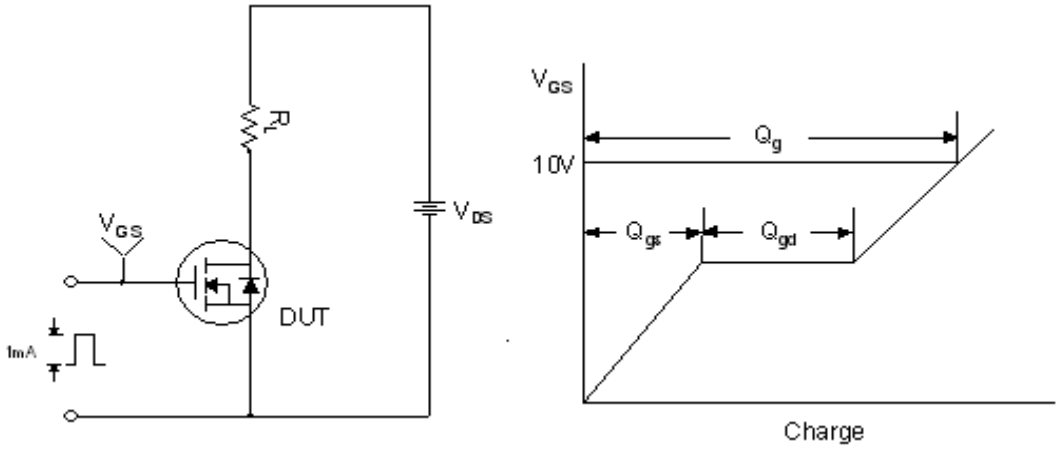


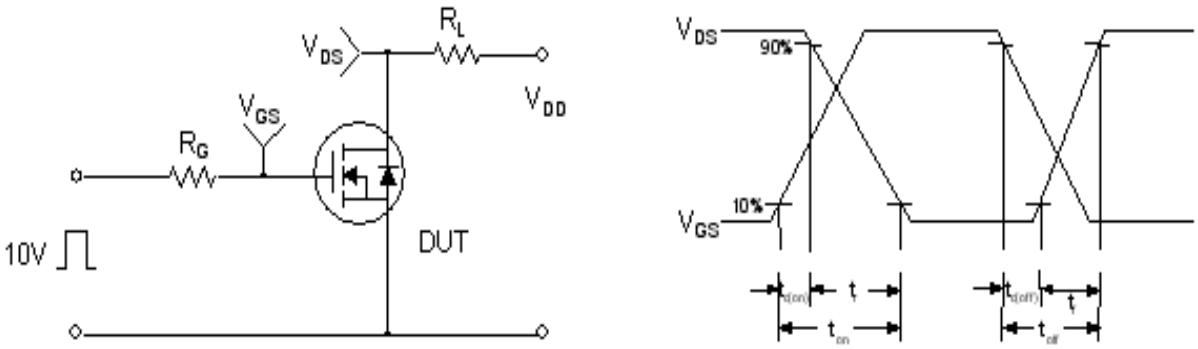
Figure 10. Transient Thermal Response Curve - FDPF8N60ZUT



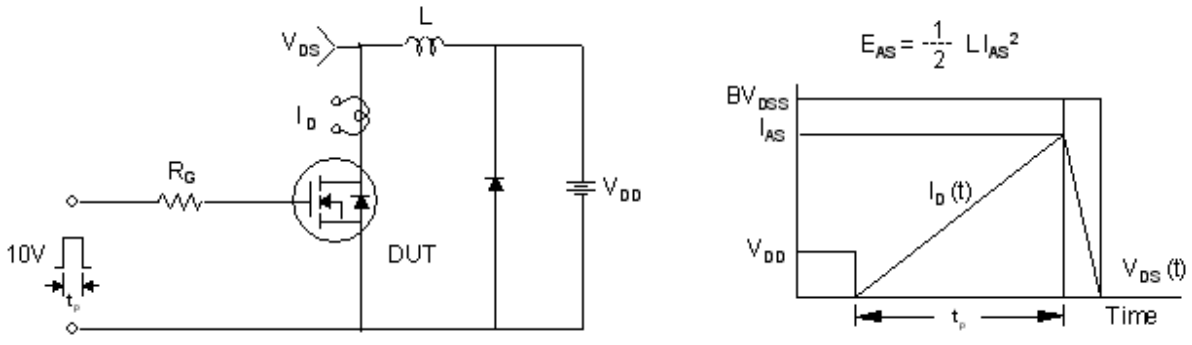
Gate Charge Test Circuit & Waveform



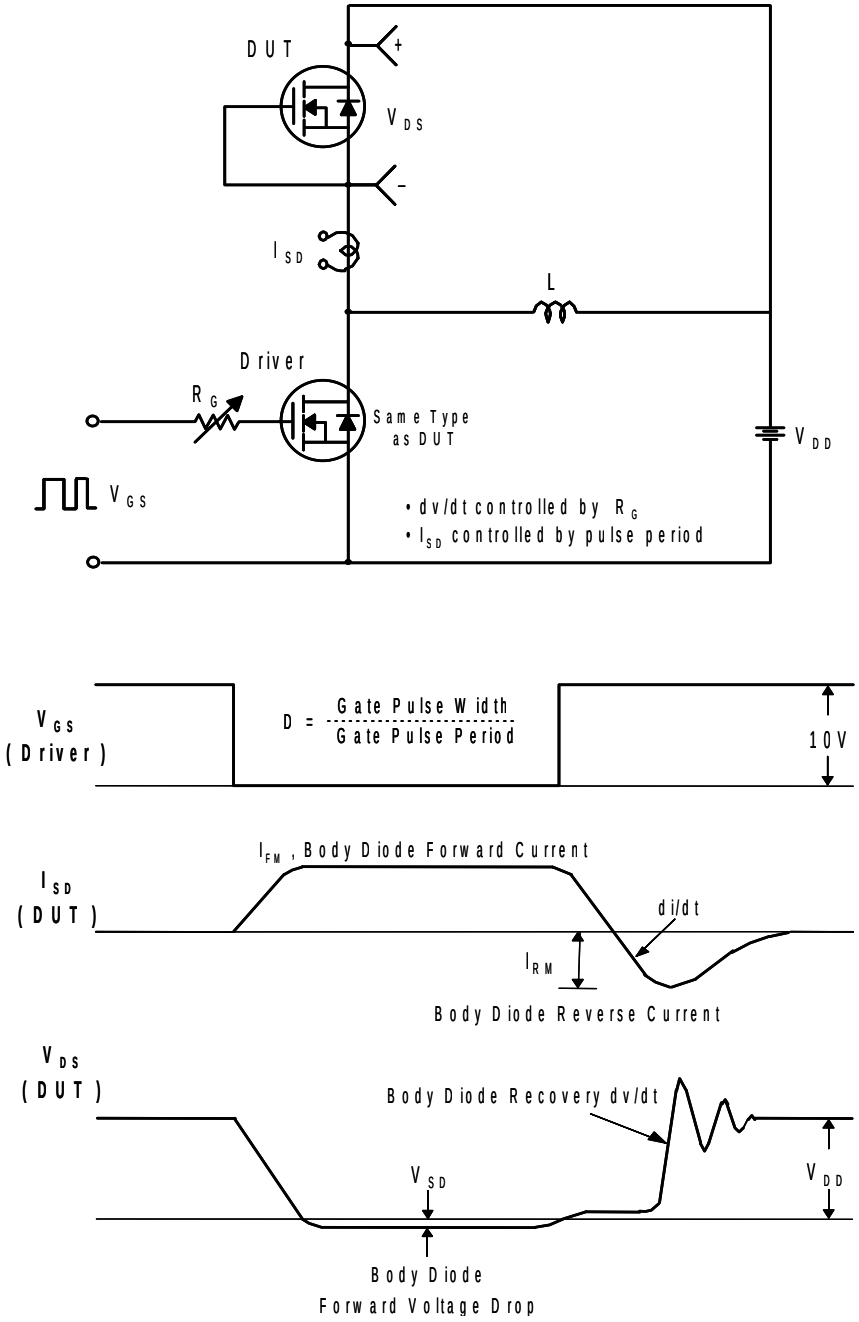
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

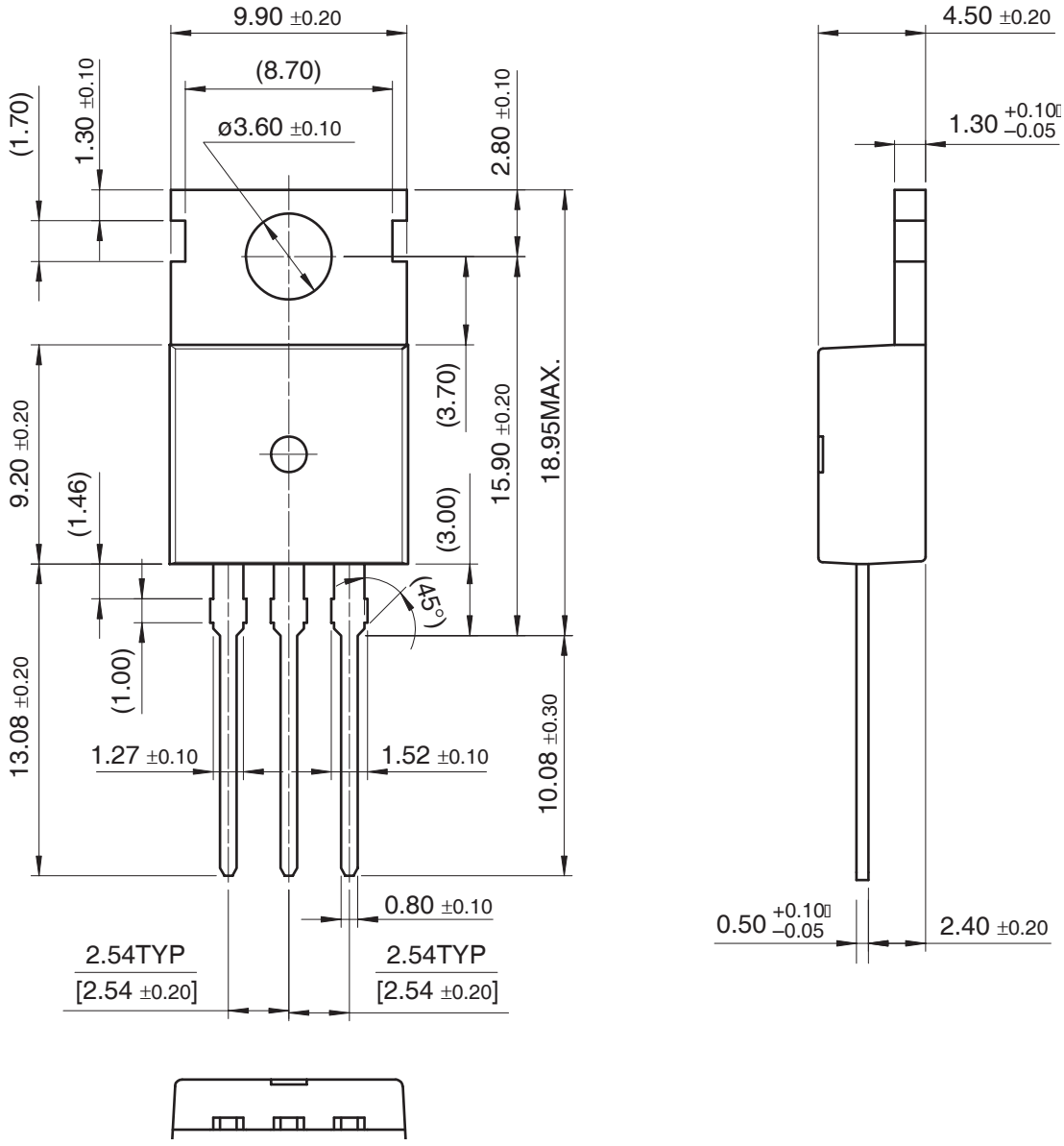


Peak Diode Recovery dv/dt Test Circuit & Waveforms



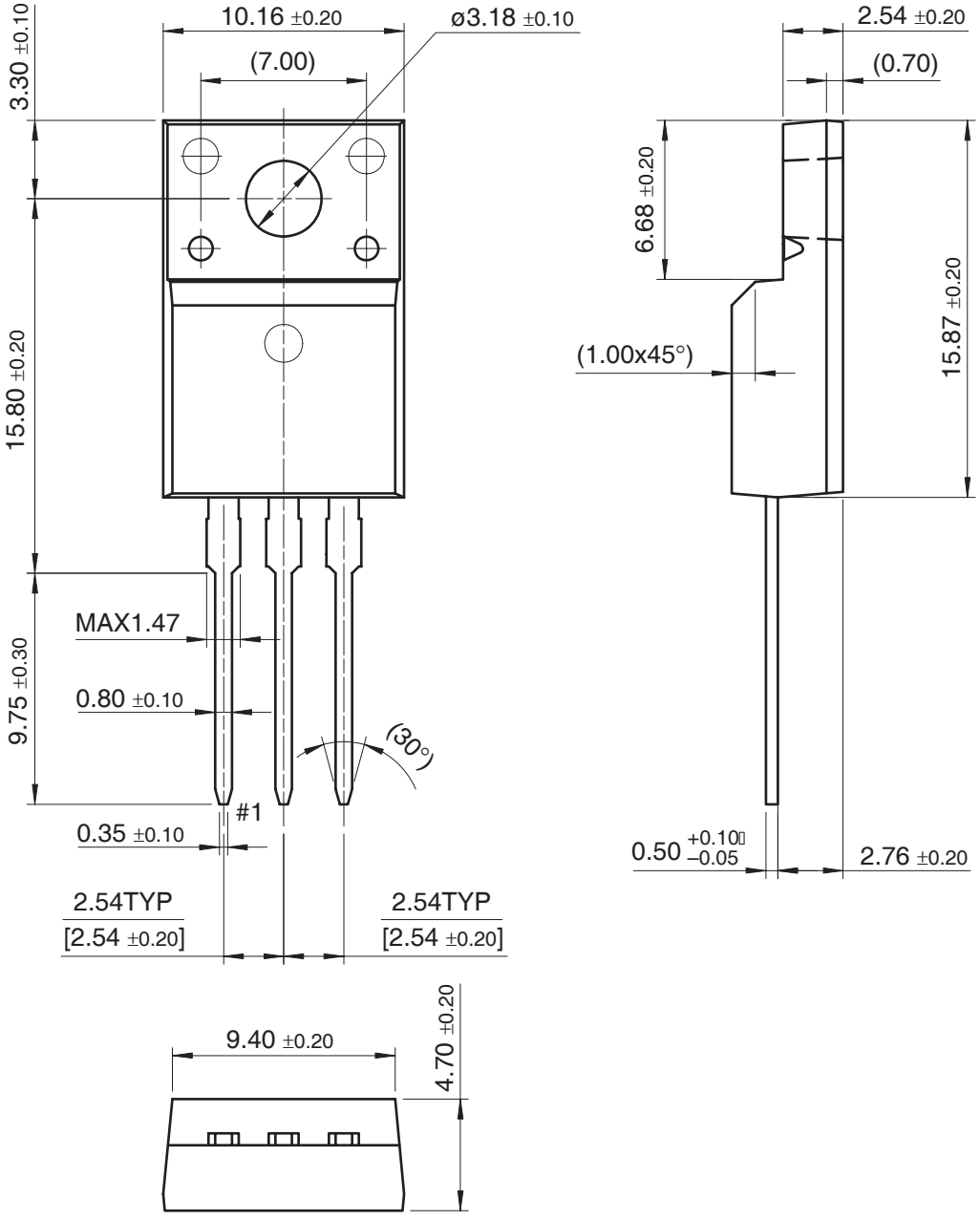
Mechanical Dimensions

TO-220



Mechanical Dimensions

TO-220F



Dimensions in Millimeters

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